



T_C =25

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V _{DS}	30	V
Gate-Source Voltage	V _{GS}	±20	V
Continuous Drain Current	I _{D@TC=25}	15	A
	I _{D@TC=75}	11	A
	I _{D@TC=100}	9.5	A
Pulsed Drain Current	I _{DM}	30	



Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	8	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	95	° C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	° C

Fig.1 Gate-Charge Characteristics

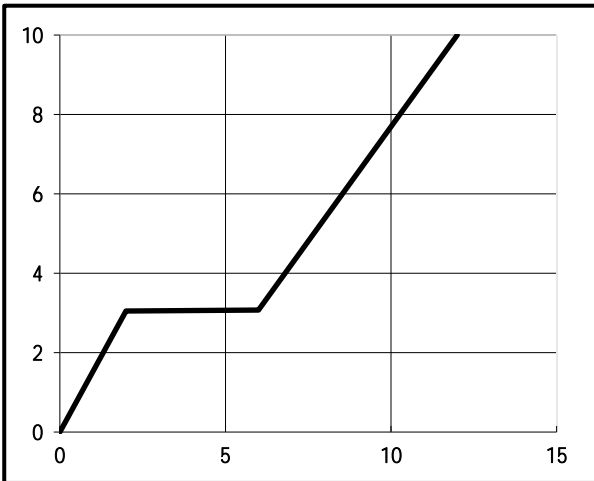


Fig.2 Capacitance Characteristics

Fig.3 Power Dissipation Derating Curve

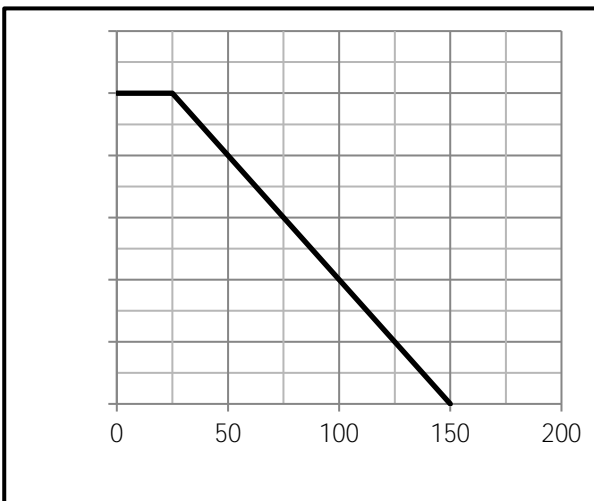


Fig.4 Typical output Characteristics

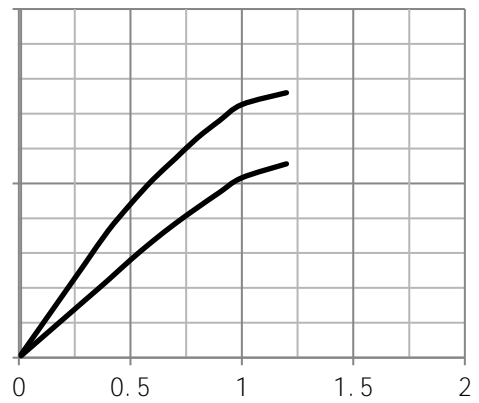


Fig.5 Threshold Voltage V.S Junction Temperature

Fig.6 Resistance V.S Drain Current

Fig.7 On-Resistance VS Gate Source Voltage

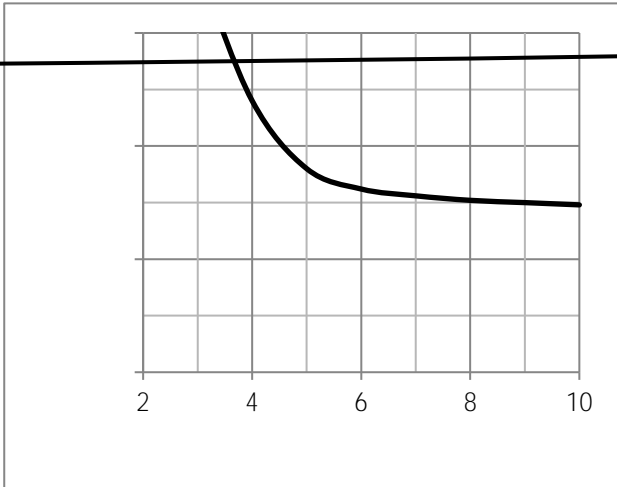


Fig.8 On-Resistance V.S Junction Temperature

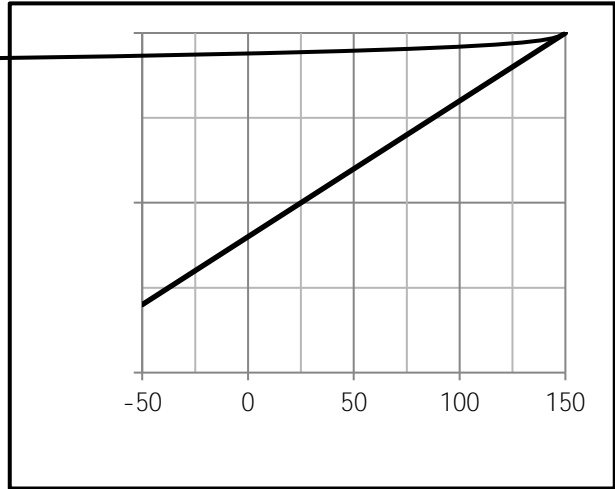


Fig.9 Switching Time Measurement Circuit

Fig.10 Gate Charge Waveform

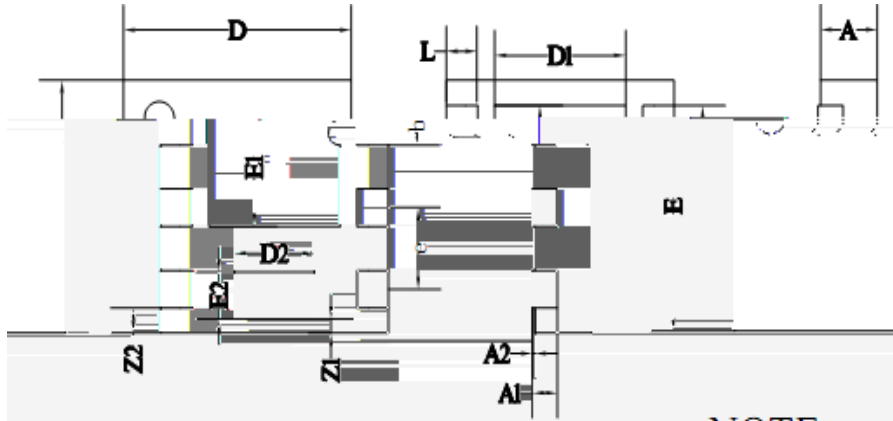
Fig.11 Avalanche Measurement Circuit

Fig.12 Avalanche Waveform



(DFN2*2)

Unit mm



NOTE:

All dimensions are in mm

NOV	MAX		MIN
200	205	D	195
200	205	E	195
115	120	D1	110
125	130	E1	120
0.25	0.3	A	0.25
0.3	0.35	A1	0.25
0.5	0.55	A2	0.45
0.25	0.3	Z1	0.25
0.3	0.35	Z	0.25
0.5	0.55	Z2	0.45